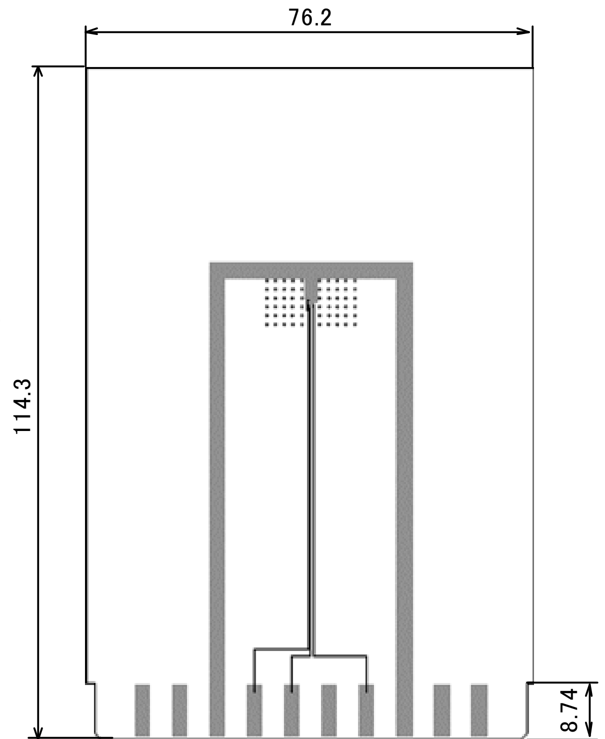
● LGA-6B01 Power Dissipation (JESD51-7)

Power dissipation data for the LGA-6B01 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board
Ambient : Natural convection
Soldering : Lead (Pb) free
Board : The board using 4 copper layer.
(76.2mm × 114.3mm・・・Area: about 8700mm2)
1st layer : No copper foil (Signal layer)
2nd layer : 70mm × 70mm_Connected to heat-sink.
3rd layer : 70mm × 70mm_Connected to heat-sink.
4th layer : No copper foil (Signal layer)
Material : Glass Epoxy(FR-4)
Thickness : 1.6mm
Through-hole φ0.2mm x 60pcs



2.Power Dissipation vs. Ambient temperature

Board Mount(Tjmax = 125℃)

AmbientTemperature (℃)	PowerDissipation Pd (mW)	θja(℃/W)
25	760	131.58
105	152